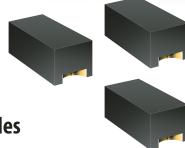


Product Change Notification

June, 2007

CHIP DIODES

Bourns Manufacturers Representatives Corporate Distributor Product Managers Americas Sales Team Asia Sales Team Europe Sales Team

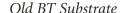


Bourns® CD0603 & CD1005 Chip Diodes Substrate Material Change

Over the past 12 months, Bourns has incurred large material cost increases for the packaging of chip diode products, especially with regard to the substrate, copper and gold materials, while lead times for raw material have also increased. To ensure continued product delivery and support to our customers, while remaining competitive on price for the Chip Diode devices, Bourns has initiated a product change from a BT substrate material to an FR5 substrate material for package assembly on the CD0603 and CD1005 chip diode part numbers. The change does not affect the electrical specifications of products, only the physical appearance.











New FR5 Substrate

Bourns will offer the new replacement FR5 devices at the same price as older BT version. Product data sheets with detailed specifications can be viewed on the Bourns website at www.bourns.com:

Switching Chip Diode Series - CD0603/1005-S Schottky Barrier Chip Diode Series - CD0603/1005-B Surface Mount Zener Diode Series - CD0603/1005-Z Surface Mount Schottky Barrier Diodes - CD1005-B0520

Last time buy date for an order is July 27, 2007, with a last date for shipments of September 28, 2007. Revised Material Declaration Sheets and updated SGS Reports are available.

ESD0710